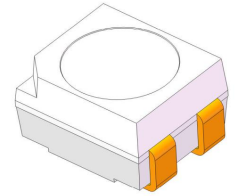


LRP4FS



采用表贴式封装，便于集成，良好的散热性能；采用垂直结构芯片，亮度高，高温下颜色漂移小；硅胶密封，透过率高，抗紫外和高温性能好；
SMD package, easy to be integrated, good heat dissipation; Vertical-chip technology, high optical output efficiency, small excursion of wave length at high temperature; Silicone sealed, high transmittance, excellent UV protection and thermal stability;

特点 | Features:

- ▲ 封装：白色 SMD 封装
Package: White SMD Package
- ▲ 视角：120°
Viewing angle: 120°
- ▲ 颜色： $\lambda_{\text{dom}} = 616 \text{ nm}$ (red)
Color: $\lambda_{\text{dom}} = 616 \text{ nm}$ (red)
- ▲ ESD：2 千伏，HBM Class 2
ESD: 2 kV, HBM Class 2
- ▲ 认证：AEC-Q102
Qualifications: AEC-Q102
- ▲ MSL：等级 2
MSL: Level 2

应用 | Applications:

- ▲ 汽车信号灯
Automotive lights
- ▲ 电器指示灯
Signaling lamp of apparatus
- ▲ 灯具
Lanterns
- ▲ 仪器、仪表盘背光显示
Dashboard backlight

目录 | Table of Contents

器件最大允许值 Maximum Ratings	3
关键指标参数 Characteristics	4
亮度分档 Brightness Groups	5
电压分档 Forward Voltage Groups	5
色度分档 Chroma Groups	5
相对光谱分布曲线 Relative Spectral Emission Curve	6
辐射特性 Radiation Characteristics	6
正向电流-正向电压 Forward current-Forward Voltage	7
正向电流-相对光通量 Forward current-Relative Luminous Flux	7
正向电流-主波长 Forward current-Dominant Wavelength	8
结温-正向电压 Junction Temperature-Forward Voltage	8
结温-相对光通量 Junction Temperature-Relative Luminous Flux	9
结温-主波长 Junction Temperature-Dominant Wavelength	9
最大容许正向电流 Max. Permissible Forward Current	10
外形尺寸 Mechanical Dimensions	11
推荐焊盘 Recommended Solder Pad	12
回流焊曲线 Reflow Soldering Profile	13
编带 Taping	14
包装信息-产品标签 Packaging Information- Product Label	15

器件最大允许值 | Maximum Ratings

参数 Parameter	符号 Symbol	值 Values	单位 Unit
工作温度 Operating temperature	T_{op}	-40-110	°C
存储温度 Storage temperature	T_{stg}	-40-110	°C
结温 P/N junction temperature	T_j	125	°C
正向电流 Forward current	I_f	70	mA
脉冲峰值电流 Surge current ($t \leq 10\mu S$; $D=0.005$; $T_s=25^\circ C$)	I_{fm}	100	mA
反向击穿电压 Reverse voltage	V_R	12	V
抗静电电压 ESD withstand voltage (acc. To ANSI/ESDA/JEDEC JS-001-HBM, Class 2)	V_{ESD}	2	kV

关键指标参数 | Characteristics (Ts=25°C, If=50mA)

参数 Parameter	符号 Symbol	值 Values	单位 Unit
峰值波长 Peak wavelength	λ_p	typ. 631	nm
主波长 Dominant wavelength	λ_d	min. 612 typ. 616 max. 624	nm
发光角度 Viewing angle at 50% I _v	2 θ	typ. 120	deg. [°]
正向电压 Forward voltage	V _f	min. 1.90 typ. 2.33 max. 2.65	V
反向漏电流 Reverse current (V _R =10V)	I _R	max. 1	μA
光通量 Luminous flux	Φ	typ. 8.1	lm
实际热阻 (P/N 结到焊接点) Thermal resistance (P/N junction to soldering point)	R _{thJs real}	max. 88	K/W
电热阻 (P/N 结到焊接点) Thermal resistance (P/N junction to soldering point)	R _{thJs ele}	max. 59	K/W

亮度分档 | Brightness Groups ($T_s=25^{\circ}\text{C}$, $I_f=50\text{mA}$)

组 Group	符号 Symbol	最小值 Min.	最大值 Max.	单位 Unit
B2	Φ_V	6.5	8.1	lm
B3	Φ_V	8.1	10.3	lm
B4	Φ_V	10.3	12.5	lm
B5	Φ_V	12.5	14.7	lm

*Ts: soldering point temperature

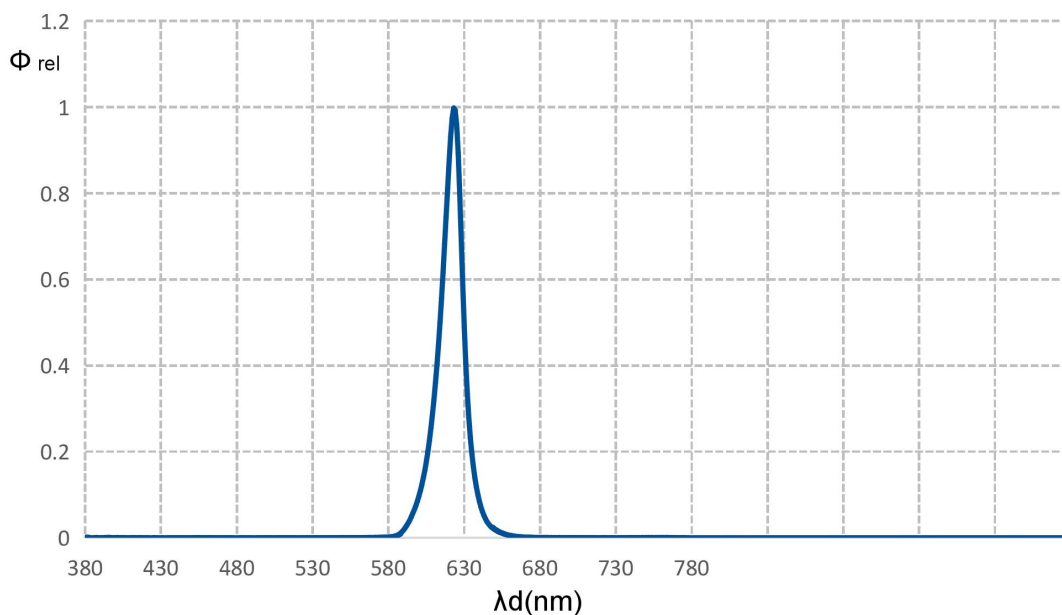
电压分档 | Forward Voltage Groups ($T_s=25^{\circ}\text{C}$, $I_f=50\text{mA}$)

组 Group	符号 Symbol	最小值 Min.	最大值 Max.	单位 Unit
V1	V_f	1.90	2.05	V
V2	V_f	2.05	2.20	V
V3	V_f	2.20	2.35	V
V4	V_f	2.35	2.50	V
V5	V_f	2.50	2.65	V

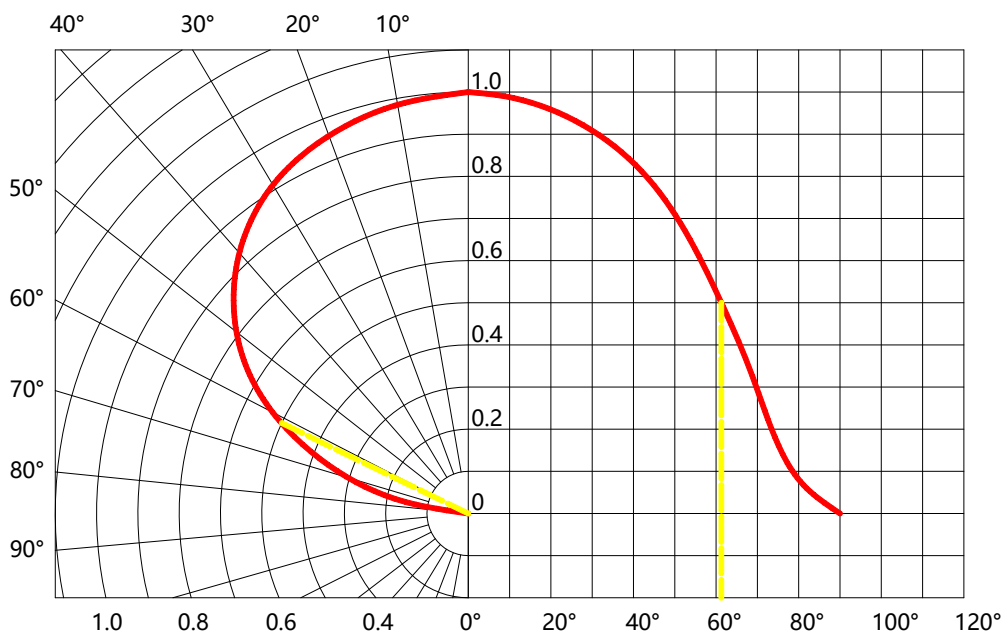
色度分档 | Chroma Groups ($T_s=25^{\circ}\text{C}$, $I_f=50\text{mA}$)

组 Group	符号 Symbol	最小值 Min.	最大值 Max.	单位 Unit
W1	λ_{dom}	612	616	nm
W2	λ_{dom}	616	620	nm
W3	λ_{dom}	620	624	nm

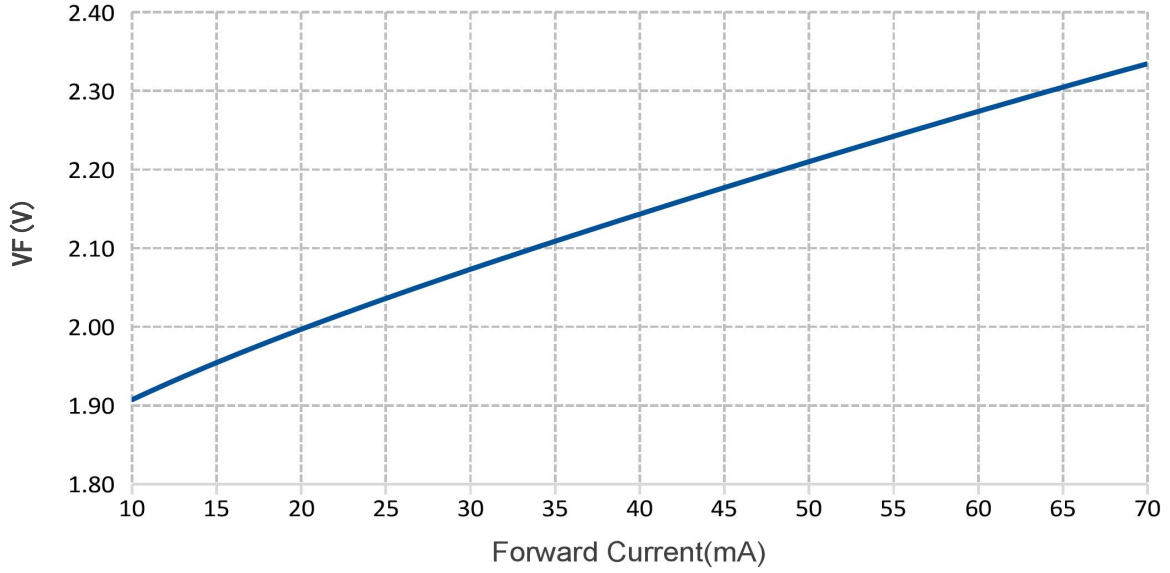
相对光谱分布曲线 | Relative Spectral Emission Curve (Ts=25°C, If=50mA)



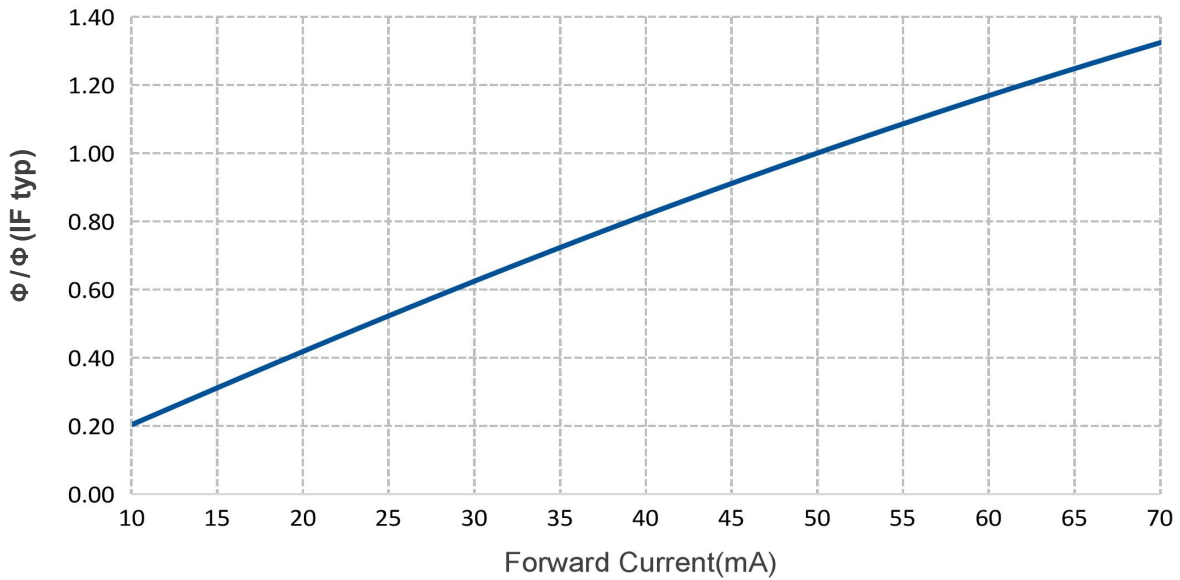
辐射特性 | Radiation Characteristics (Ts=25°C, If=50mA)

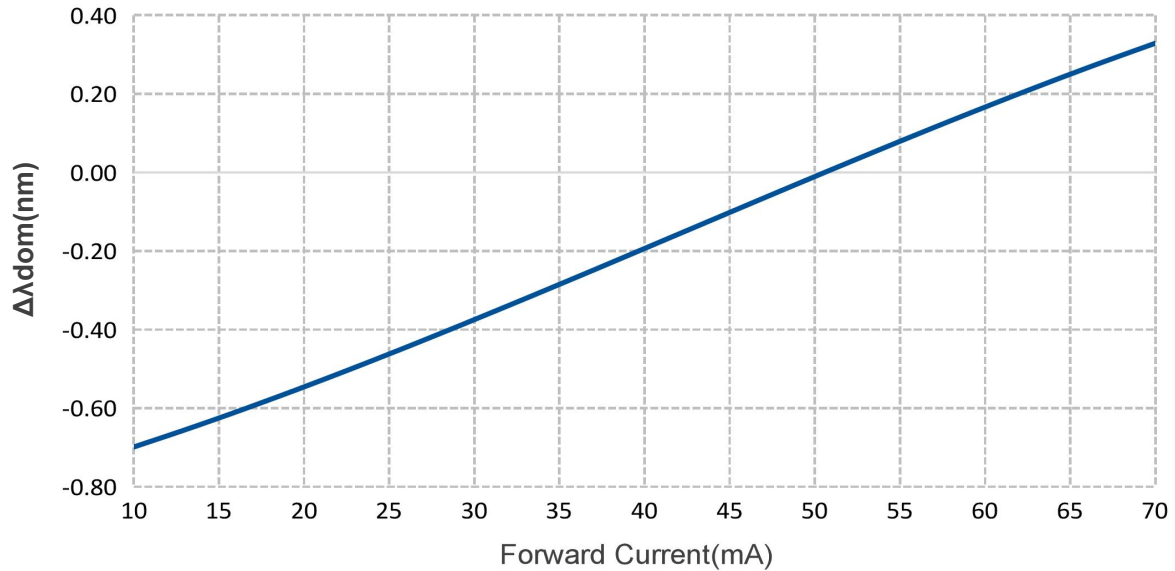
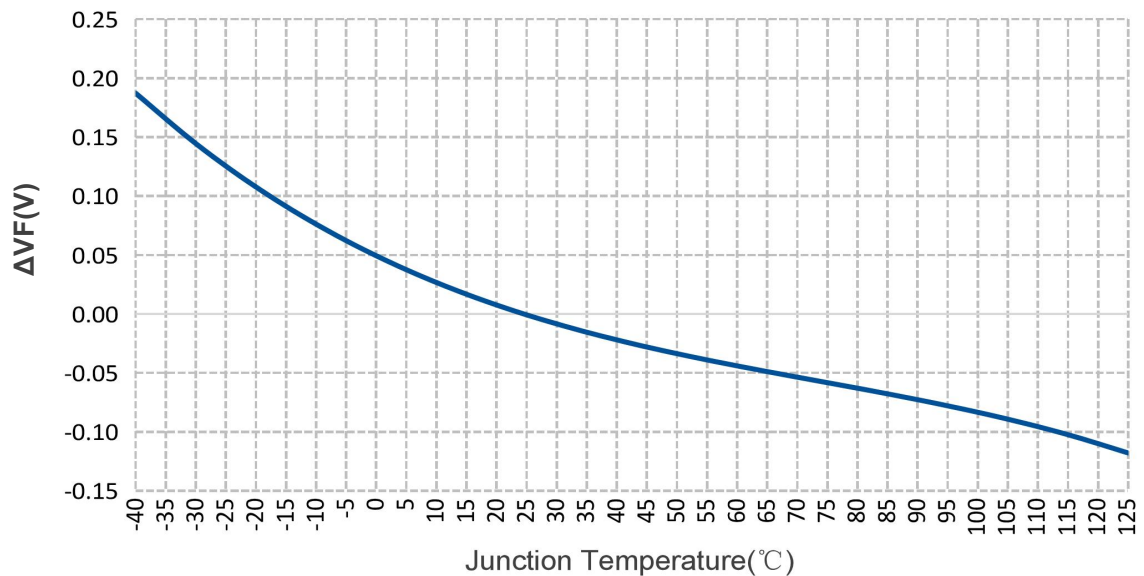


正向电流-正向电压 | Forward current-Forward Voltage (Ts=25°C)

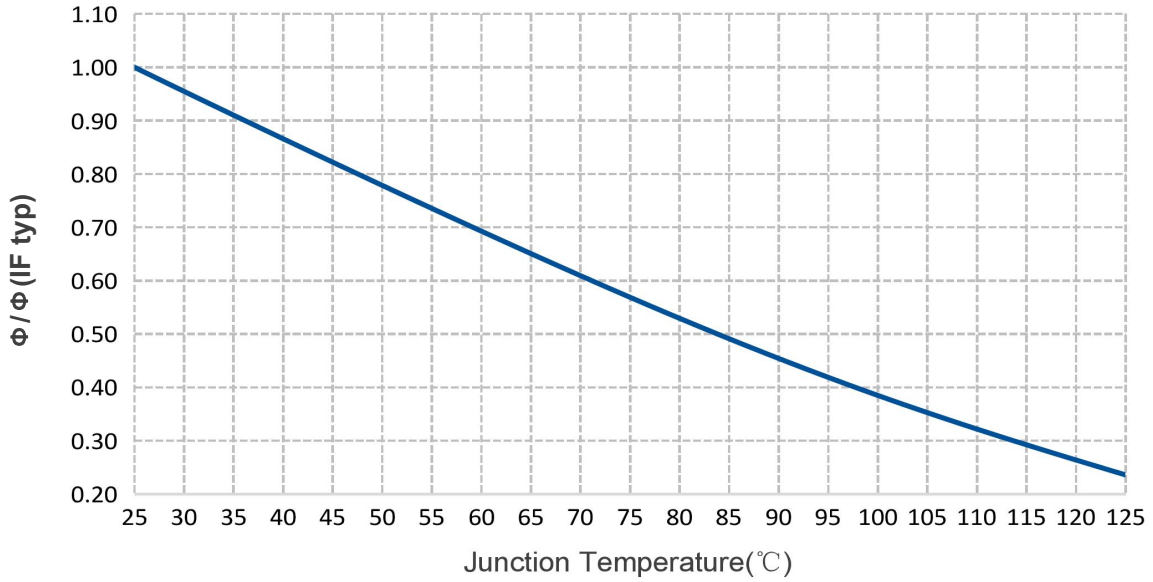


正向电流-相对光通量 | Forward current-Relative Luminous Flux (Ts=25°C)

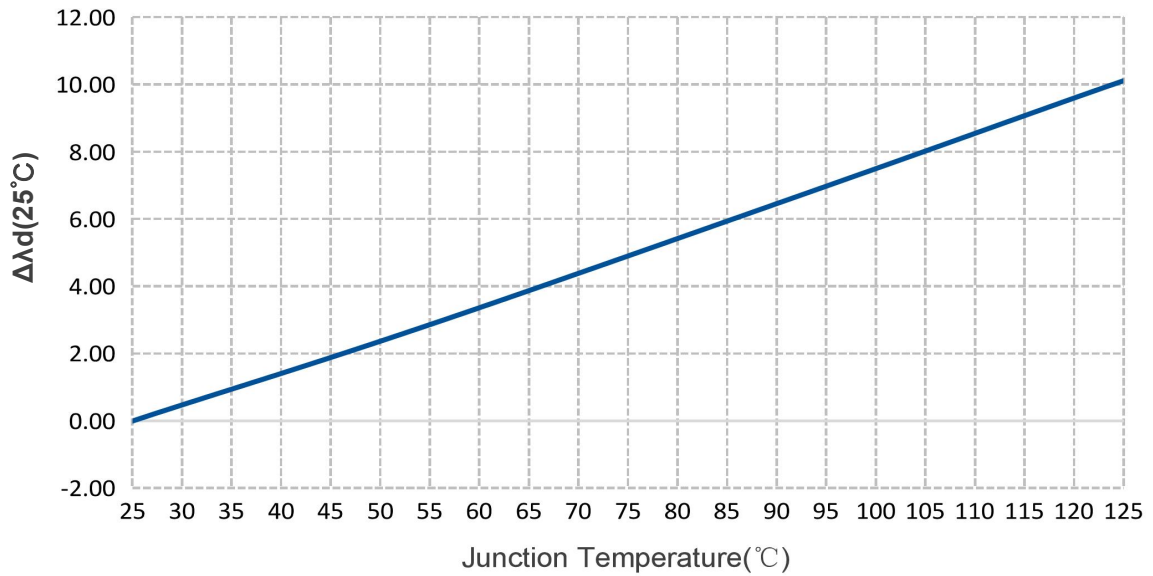


正向电流-主波长 | Forward current-Dominant Wavelength ($T_s=25^\circ\text{C}$)结温-正向电压 | Junction Temperature-Forward Voltage ($I_f=50\text{mA}$)

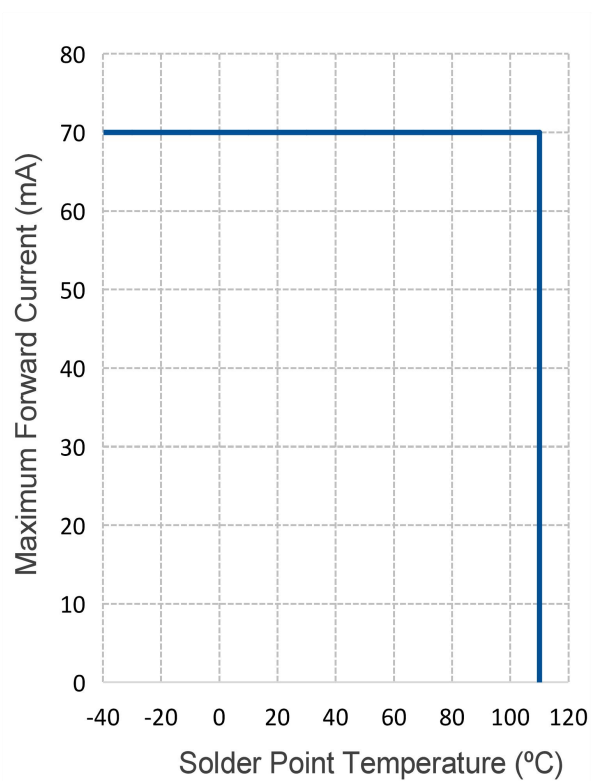
结温-相对光通量 | Junction Temperature-Relative Luminous Flux (If=50mA)



结温-主波长 | Junction Temperature-Dominant Wavelength (If=50mA)

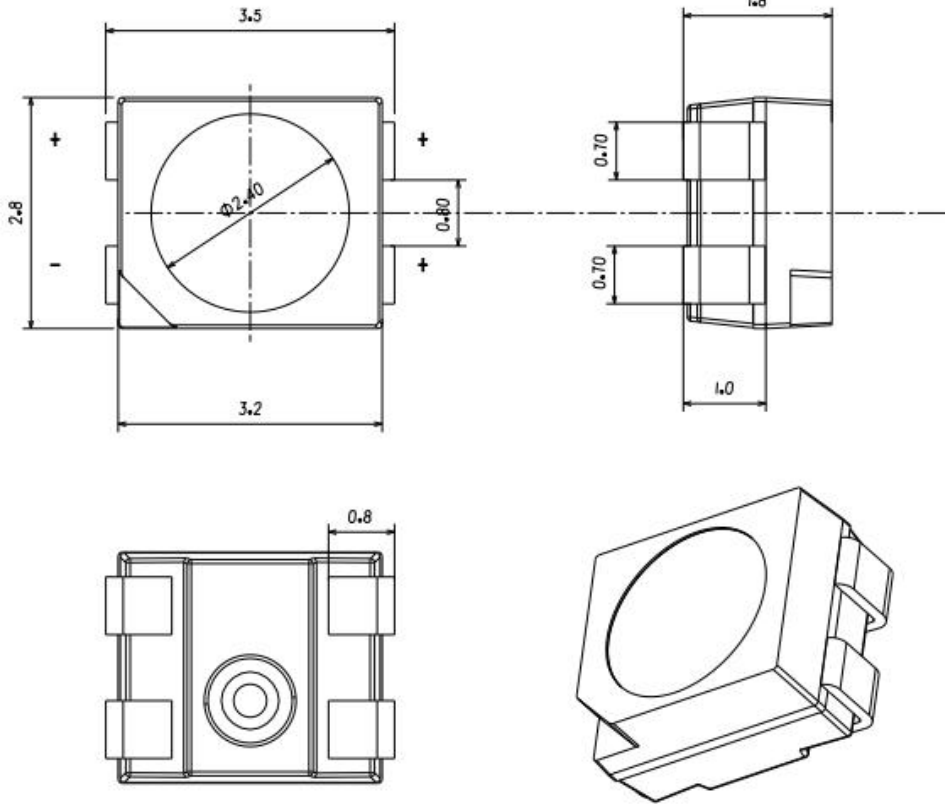


最大容许正向电流 | Max. Permissible Forward Current



外形尺寸 | Mechanical Dimensions

单位 | Unit: mm

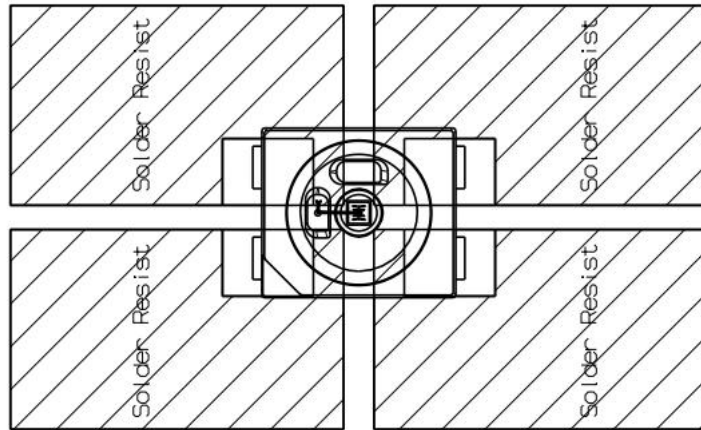
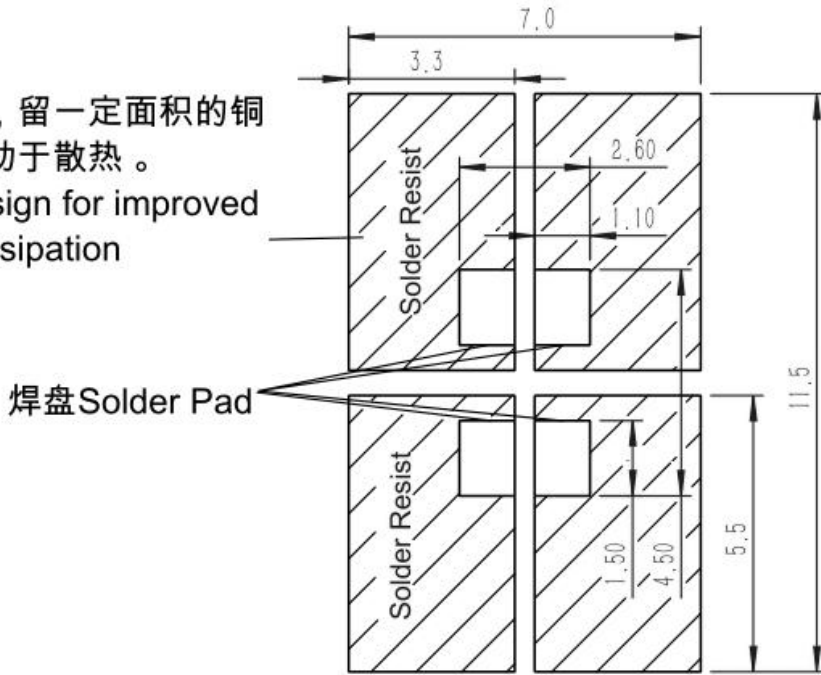


尺寸 Size	公差 Tolerance
.	$\pm 0.1\text{mm}$
*.**	$\pm 0.05\text{mm}$

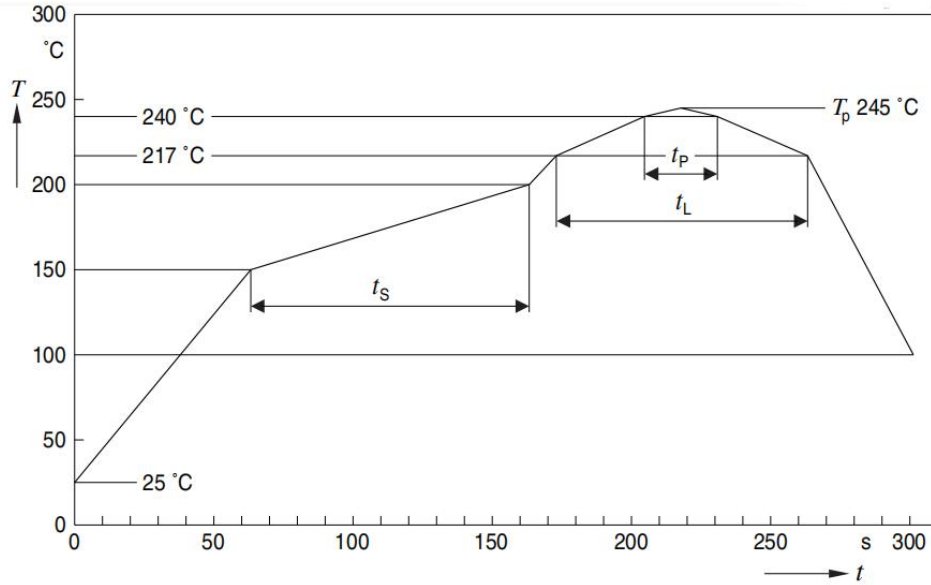
推荐焊盘 | Recommended Solder Pad

单位 | Unit: mm

阻焊层，留一定面积的铜箔层有助于散热。
Pad design for improved heat dissipation



回流焊曲线 | Reflow Soldering Profile

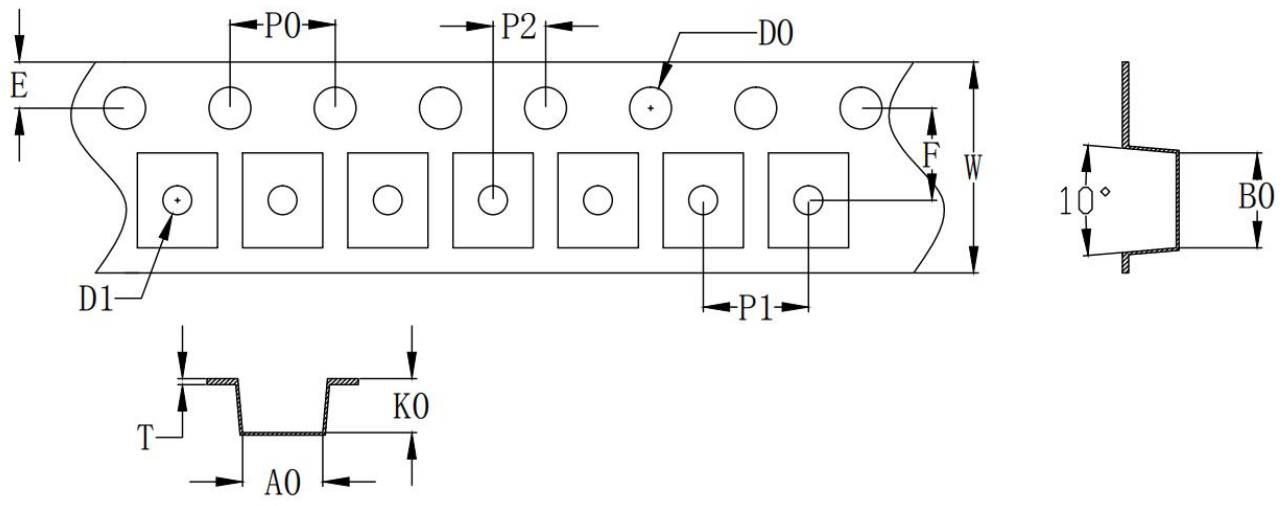
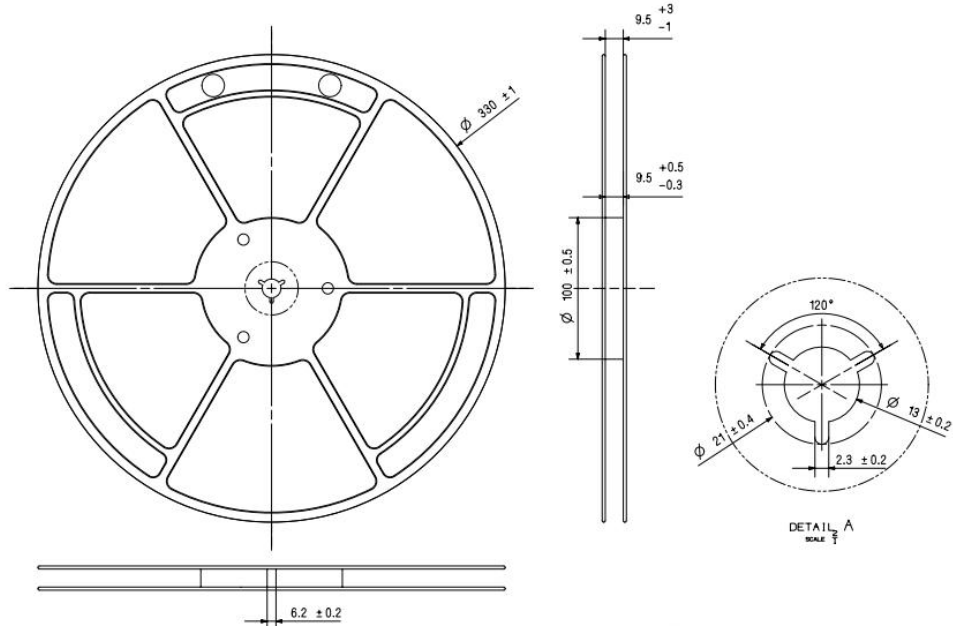


回流焊步骤 Profile Feature	符号 Symbol	无铅回流焊 (SnAgCu) Pb-Free (SnAgCu) Assembly			单位 Unit
		最小值 Min.	设定值 Reco.	最大值 Max.	
预热升温速率 25 °C to 150 °C Ramp-up rate to preheat			2	3	K/s
升温时间 (T _{smin} -T _{smax})	t _s	60	100	120	s
从 T _{smax} 升温到最高温度的速率 Ramp-up rate to peak			2	3	K/s
达到液相的温度 Liquidus temperature			217		°C
在液相温度以上的时间 Time above liquidus temperature	t _L		80	100	s
最高温度 Peak temperature	T _p		245	260	°C
在高于最高温度 5°C 范围内停留的时间 Time within 5 °C of the specified peak temperature TP - 5 K	t _p	10	20	30	s
降到 100°C 的速率 Ramp-down rate* TP to 100 °C			3	6	K/s
从最高温降到 25°C 的时间 Time 25 °C to TP				480	s

*LED complies to MSL Level 2 (JEDEC J-STD-020E)

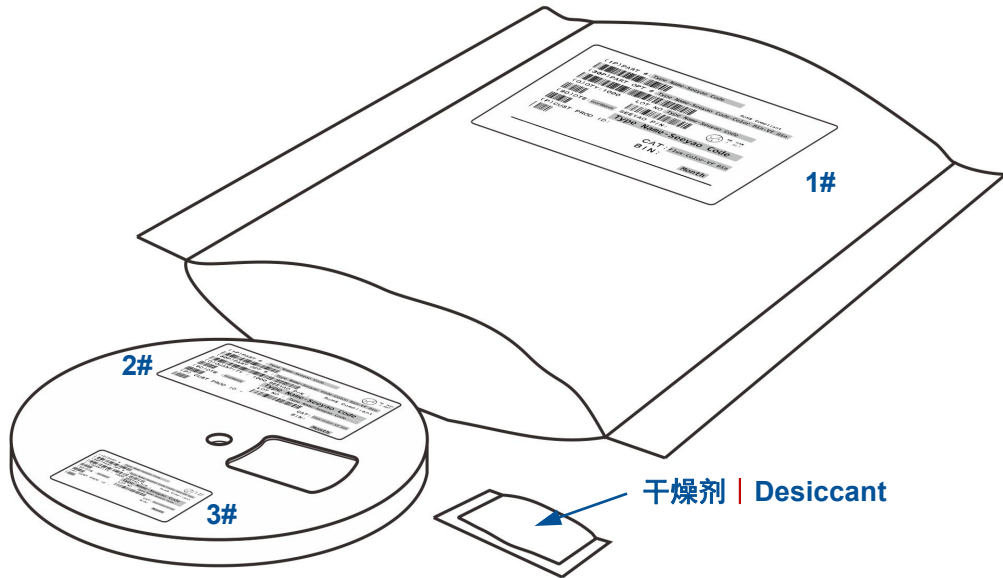
编带 | Taping

单位 | Unit: mm



ITEM	W	A0	B0	K0	E	F	D0	D1	P0	P1	P2	T
DIM	8.00	3.05	3.70	2.05	1.75	3.50	1.50	1.10	4.00	4.00	2.00	0.22
TOLE	+0.10 -0.10	+0.10 -0.10	+0.10 -0.10	+0.10 -0.10	+0.10 -0.10	+0.10 -0.10	+0.10 -0	+0.10 -0.10	+0.10 -0.10	+0.10 -0.10	+0.10 -0.10	+0.03 -0.03

包装信息-产品标签 | Packaging Information- Product Label



标签 1# | Label 1#

标签 2# | Label 2#

标签 3# | Label 3#

SEEYAO PN: Type Name-See Yao Code	
BATCH NO: SALME0123456789	
(Q)QUANTITY: QTY Seal Date:YYMMDD	
(9D)DATE CODE: YYWW	
(33P)CAT CODE: Flux-Color-Vf	
(1T)LOT NO: Bin012345678K601234	Month

SEEYAO PN: Type Name-See Yao Code	
BATCH NO: SALME0123456789	
(Q)QUANTITY: QTY Seal Date:YYMMDD	
(9D)DATE CODE: YYWW	
(33P)CAT CODE: Flux-Color-Vf	
(1T)LOT NO: Bin012345678K601234	Month

DT:012345K60123		
Qty:qty		
Bin:CAT CODE		
Type Name-See Yao Code		
SALME0123456789		
Bin012345678K601234		